

# 74LVC1G07-Q100

Buffer with open-drain output

Rev. 1 — 23 May 2013

Product data sheet

## 1. General description

The 74LVC1G07-Q100 provides the non-inverting buffer.

The output of this device is an open drain and can be connected to other open-drain outputs to implement active-LOW wired-OR or active-HIGH wired-AND functions.

Inputs can be driven from either 3.3 V or 5 V devices. This feature allows the use of this device in a mixed 3.3 V and 5 V environment.

Schmitt-trigger action at all inputs makes the circuit tolerant for slower input rise and fall time.

This device is fully specified for partial power-down applications using  $I_{OFF}$ . The  $I_{OFF}$  circuitry disables the output, preventing the damaging backflow current through the device when it is powered down.

This product has been qualified to the Automotive Electronics Council (AEC) standard Q100 (Grade 1) and is suitable for use in automotive applications.

## 2. Features and benefits

- Automotive product qualification in accordance with AEC-Q100 (Grade 1)
  - ◆ Specified from  $-40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$  and from  $-40\text{ }^{\circ}\text{C}$  to  $+125\text{ }^{\circ}\text{C}$
- Wide supply voltage range from 1.65 V to 5.5 V
- 5 V tolerant input/output for interfacing with 5 V logic
- High noise immunity
- Complies with JEDEC standard:
  - ◆ JESD8-7 (1.65 V to 1.95 V)
  - ◆ JESD8-5 (2.3 V to 2.7 V)
  - ◆ JESD8-B/JESD36 (2.7 V to 3.6 V)
- ESD protection:
  - ◆ MIL-STD-883, method 3015 exceeds 2000 V
  - ◆ HBM JESD22-A114F exceeds 2000 V
  - ◆ MM JESD22-A115-A exceeds 200 V (C = 200 pF, R = 0  $\Omega$ )
- $-24\text{ mA}$  output drive ( $V_{CC} = 3.0\text{ V}$ )
- CMOS low power consumption
- Latch-up performance exceeds 250 mA
- Direct interface with TTL levels
- Inputs accept voltages up to 5 V
- Multiple package options



## 3. Ordering information

Table 1. Ordering information

Type number	Package			Version
	Temperature range	Name	Description	
74LVC1G07GW-Q100	-40 °C to +125 °C	TSSOP5	plastic thin shrink small outline package; 5 leads; body width 1.25 mm	SOT353-1
74LVC1G07GV-Q100	-40 °C to +125 °C	SC-74A	plastic surface-mounted package; 5 leads	SOT753

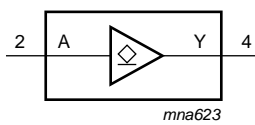
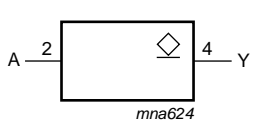
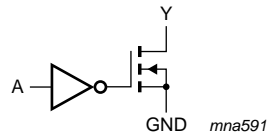
## 4. Marking

Table 2. Marking

Type number	Marking code <sup>[1]</sup>
74LVC1G07GW-Q100	VS
74LVC1G07GV-Q100	V07

[1] The pin 1 indicator is located on the lower left corner of the device, below the marking code.

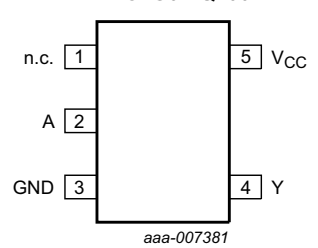
## 5. Functional diagram

 <p><i>mna623</i></p>	 <p><i>mna624</i></p>	 <p><i>mna591</i></p>
<p><b>Fig 1. Logic symbol</b></p>	<p><b>Fig 2. IEC logic symbol</b></p>	<p><b>Fig 3. Logic diagram</b></p>

## 6. Pinning information

### 6.1 Pinning

**74LVC1G07-Q100**



*aaa-007381*

**Fig 4. Pin configuration SOT353-1 and SOT753**

## 6.2 Pin description

**Table 3.** Pin description

Symbol	Pin	Description
n.c.	1	not connected
A	2	data input
GND	3	ground (0 V)
Y	4	data output
V <sub>CC</sub>	5	supply voltage

## 7. Functional description

**Table 4.** Function table<sup>[1]</sup>

Input A	Output Y
L	L
H	Z

[1] H = HIGH voltage level; L = LOW voltage level; Z = high-impedance OFF-state.

## 8. Limiting values

**Table 5.** Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>CC</sub>	supply voltage		-0.5	+6.5	V
I <sub>IK</sub>	input clamping current	V <sub>I</sub> < 0 V	-50	-	mA
V <sub>I</sub>	input voltage		<sup>[1]</sup> -0.5	+6.5	V
I <sub>OK</sub>	output clamping current	V <sub>O</sub> < 0 V	-50	-	mA
V <sub>O</sub>	output voltage	Active mode	<sup>[1]</sup> -0.5	+6.5	V
		Power-down mode	<sup>[1][2]</sup> -0.5	+6.5	V
I <sub>O</sub>	output current	V <sub>O</sub> = 0 V to 6.5 V	-	50	mA
I <sub>CC</sub>	supply current		-	100	mA
I <sub>GND</sub>	ground current		-100	-	mA
T <sub>stg</sub>	storage temperature		-65	+150	°C
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> = -40 °C to +125 °C	<sup>[3]</sup> -	250	mW

[1] The minimum input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] When V<sub>CC</sub> = 0 V (Power-down mode), the output voltage can be 5.5 V in normal operation.

[3] For TSSOP5 and SC-74A packages: above 87.5 °C the value of P<sub>tot</sub> derates linearly with 4.0 mW/K.

## 9. Recommended operating conditions

Table 6. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CC}$	supply voltage		1.65	-	5.5	V
$V_I$	input voltage		0	-	5.5	V
$V_O$	output voltage	Active mode	0	-	5.5	V
		Power-down mode; $V_{CC} = 0$ V	0	-	5.5	V
$T_{amb}$	ambient temperature		-40	-	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{CC} = 1.65$ V to 2.7 V	-	-	20	ns/V
		$V_{CC} = 2.7$ V to 5.5 V	-	-	10	ns/V

## 10. Static characteristics

Table 7. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	
$V_{IH}$	HIGH-level input voltage	$V_{CC} = 1.65$ V to 1.95 V	$0.65V_{CC}$	-	-	$0.65V_{CC}$	-	V
		$V_{CC} = 2.3$ V to 2.7 V	1.7	-	-	1.7	-	V
		$V_{CC} = 2.7$ V to 3.6 V	2.0	-	-	2.0	-	V
		$V_{CC} = 4.5$ V to 5.5 V	$0.7V_{CC}$	-	-	$0.7V_{CC}$	-	V
$V_{IL}$	LOW-level input voltage	$V_{CC} = 1.65$ V to 1.95 V	-	-	$0.35V_{CC}$	-	$0.35V_{CC}$	V
		$V_{CC} = 2.3$ V to 2.7 V	-	-	0.7	-	0.7	V
		$V_{CC} = 2.7$ V to 3.6 V	-	-	0.8	-	0.8	V
		$V_{CC} = 4.5$ V to 5.5 V	-	-	$0.3V_{CC}$	-	$0.3V_{CC}$	V
$V_{OL}$	LOW-level output voltage	$V_I = V_{IH}$ or $V_{IL}$						
		$I_O = 100$ $\mu$ A; $V_{CC} = 1.65$ V to 5.5 V	-	-	0.10	-	0.10	V
		$I_O = 4$ mA; $V_{CC} = 1.65$ V	-	-	0.45	-	0.70	V
		$I_O = 8$ mA; $V_{CC} = 2.3$ V	-	-	0.30	-	0.45	V
		$I_O = 12$ mA; $V_{CC} = 2.7$ V	-	-	0.40	-	0.60	V
		$I_O = 24$ mA; $V_{CC} = 3.0$ V	-	-	0.55	-	0.80	V
$I_I$	input leakage current	$V_I = 5.5$ V or GND; $V_{CC} = 0$ V to 5.5 V	<sup>[2]</sup>	-	$\pm 0.1$	$\pm 5$	-	$\pm 100$ $\mu$ A
		$V_I = V_{IH}$ or $V_{IL}$ ; $V_O = V_{CC}$ or GND; $V_{CC} = 5.5$ V	-	$\pm 0.1$	$\pm 10$	-	$\pm 100$	$\mu$ A
$I_{OFF}$	power-off leakage current	$V_I$ or $V_O = 5.5$ V; $V_{CC} = 0$ V	-	$\pm 0.1$	$\pm 10$	-	$\pm 200$	$\mu$ A

**Table 7. Static characteristics ...continued**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	
I <sub>CC</sub>	supply current	V <sub>I</sub> = 5.5 V or GND; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 1.65 V to 5.5 V	-	0.1	10	-	200	μA
ΔI <sub>CC</sub>	additional supply current	per pin; V <sub>I</sub> = V <sub>CC</sub> - 0.6 V; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 2.3 V to 5.5 V	[2]	5	500	-	5000	μA
C <sub>I</sub>	input capacitance	V <sub>CC</sub> = 3.3 V; V <sub>I</sub> = GND to V <sub>CC</sub>	-	5.0	-	-	-	pF

[1] All typical values are measured at T<sub>amb</sub> = 25 °C.

[2] These typical values are measured at V<sub>CC</sub> = 3.3 V.

## 11. Dynamic characteristics

**Table 8. Dynamic characteristics**

Voltages are referenced to GND (ground = 0 V); for load circuit see [Figure 6](#).

Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit	
			Min	Typ <sup>[1]</sup>	Max	Min	Max		
t <sub>pd</sub>	propagation delay	A to Y; see <a href="#">Figure 5</a>	[2]						
		V <sub>CC</sub> = 1.65 V to 1.95 V		1.0	2.6	6.7	1.0	8.4	ns
		V <sub>CC</sub> = 2.3 V to 2.7 V		0.5	1.7	5.5	0.5	7.0	ns
		V <sub>CC</sub> = 2.7 V		0.5	2.3	4.7	0.5	6.0	ns
		V <sub>CC</sub> = 3.0 V to 3.6 V		0.5	2.2	4.2	0.5	5.5	ns
		V <sub>CC</sub> = 4.5 V to 5.5 V		0.5	1.6	3.5	0.5	4.5	ns
C <sub>PD</sub>	power dissipation capacitance	V <sub>I</sub> = GND to V <sub>CC</sub> ; V <sub>CC</sub> = 3.3 V	[3]	-	7.0	-	-	-	pF

[1] Typical values are measured at T<sub>amb</sub> = 25 °C and V<sub>CC</sub> = 1.8 V, 2.5 V, 2.7 V, 3.3 V and 5.0 V respectively.

[2] t<sub>pd</sub> is the same as t<sub>PLZ</sub> and t<sub>PZL</sub>.

[3] C<sub>PD</sub> is used to determine the dynamic power dissipation (P<sub>D</sub> in μW).

$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \sum(C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

f<sub>i</sub> = input frequency in MHz;

f<sub>o</sub> = output frequency in MHz;

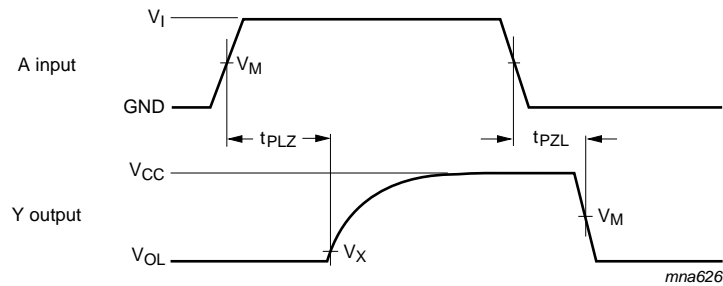
C<sub>L</sub> = output load capacitance in pF;

V<sub>CC</sub> = supply voltage in V;

N = number of inputs switching;

∑(C<sub>L</sub> × V<sub>CC</sub><sup>2</sup> × f<sub>o</sub>) = sum of outputs.

## 12. Waveforms



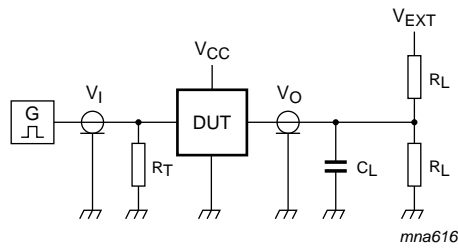
Measurement points are given in [Table 9](#).

$V_{OL}$  is the typical output voltage level that occurs with the output load.

**Fig 5. The input (A) to output (Y) propagation delays**

**Table 9. Measurement points**

Supply voltage	Input	Output	
$V_{CC}$	$V_M$	$V_M$	$V_X$
1.65 V to 1.95 V	$0.5V_{CC}$	$0.5V_{CC}$	$V_{OL} + 0.15 V$
2.3 V to 2.7 V	$0.5V_{CC}$	$0.5V_{CC}$	$V_{OL} + 0.15 V$
2.7 V	1.5 V	1.5 V	$V_{OL} + 0.3 V$
3.0 V to 3.6 V	1.5 V	1.5 V	$V_{OL} + 0.3 V$
4.5 V to 5.5 V	$0.5V_{CC}$	$0.5V_{CC}$	$V_{OL} + 0.3 V$



Test data is given in [Table 10](#).

Definitions for test circuit:

$R_L$  = Load resistance.

$C_L$  = Load capacitance including jig and probe capacitance.

$R_T$  = Termination resistance should be equal to the output impedance  $Z_o$  of the pulse generator.

$V_{EXT}$  = External voltage for measuring switching times.

**Fig 6. Test circuit for measuring switching times**

**Table 10. Test data**

Supply voltage	Input		Load		$V_{EXT}$
$V_{CC}$	$V_I$	$t_r, t_f$	$C_L$	$R_L$	$t_{PZL}, t_{PLZ}$
1.65 V to 1.95 V	$V_{CC}$	$\leq 2.0$ ns	30 pF	1 k $\Omega$	$2V_{CC}$
2.3 V to 2.7 V	$V_{CC}$	$\leq 2.0$ ns	30 pF	500 $\Omega$	$2V_{CC}$
2.7 V	2.7 V	$\leq 2.5$ ns	50 pF	500 $\Omega$	6 V
3.0 V to 3.6 V	2.7 V	$\leq 2.5$ ns	50 pF	500 $\Omega$	6 V
4.5 V to 5.5 V	$V_{CC}$	$\leq 2.5$ ns	50 pF	500 $\Omega$	$2V_{CC}$

13. Package outline

TSSOP5: plastic thin shrink small outline package; 5 leads; body width 1.25 mm

SOT353-1

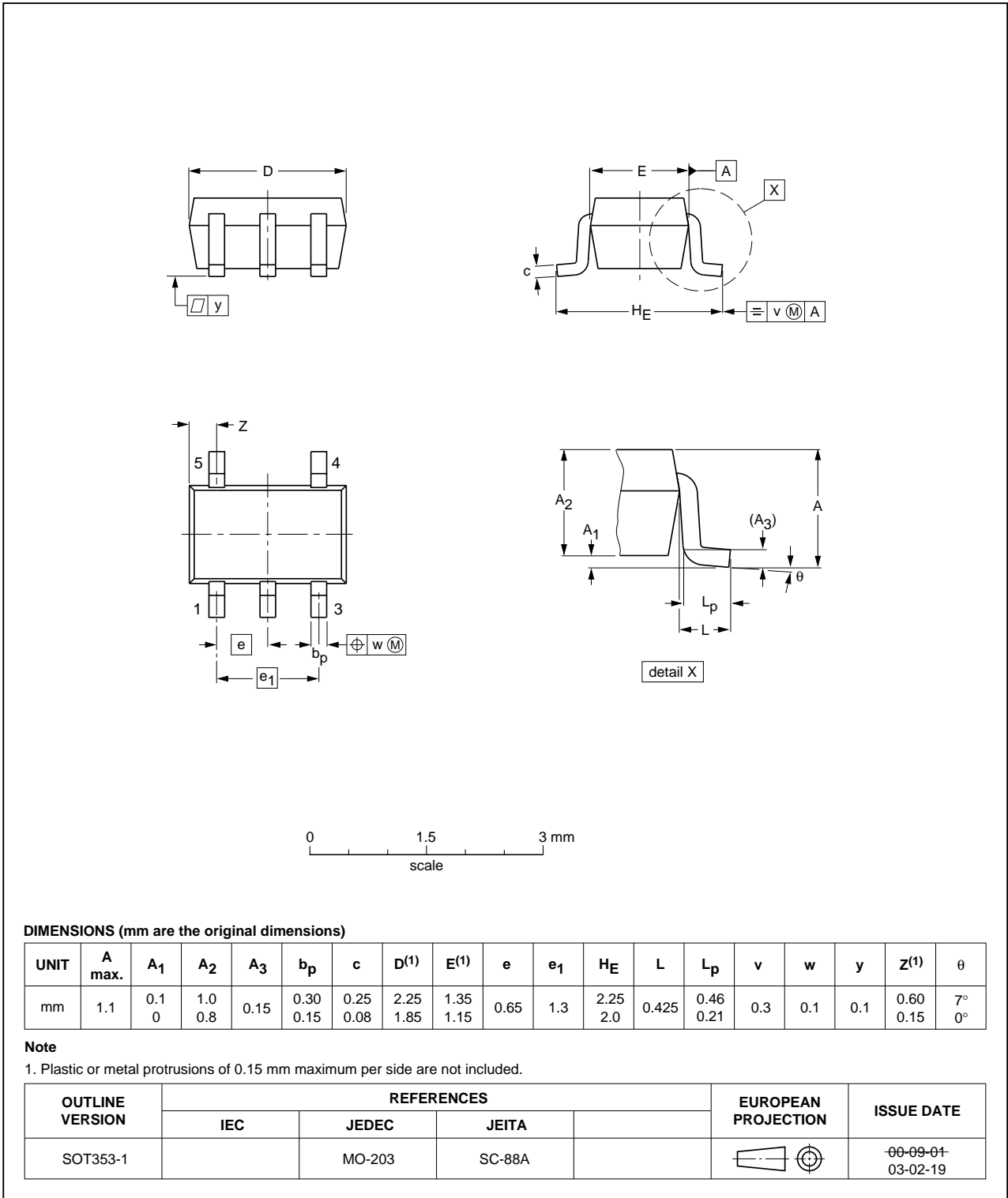


Fig 7. Package outline SOT353-1 (TSSOP5)



Plastic surface-mounted package; 5 leads

SOT753

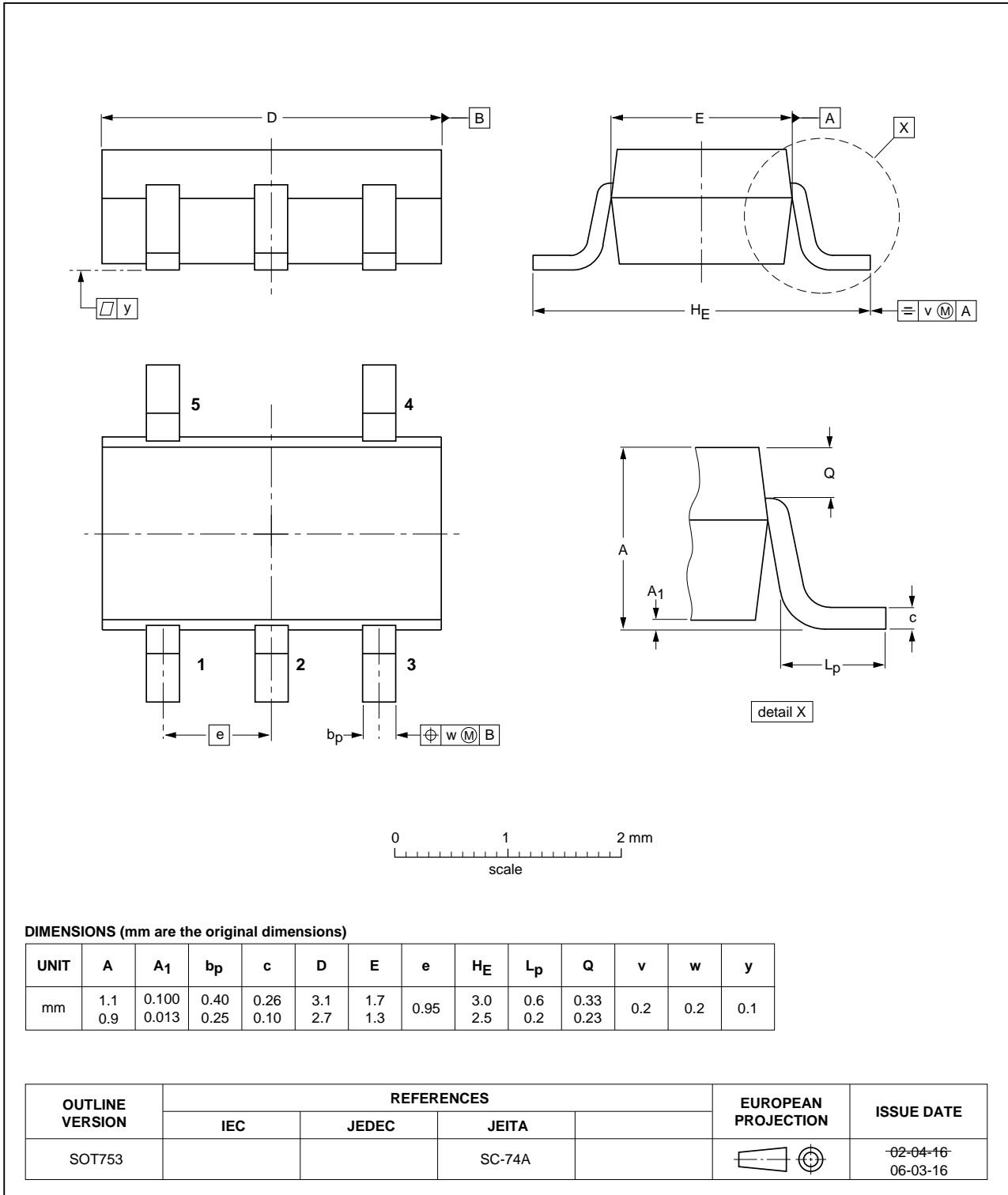


Fig 8. Package outline SOT753 (SC-74A)

## 14. Abbreviations

Table 11. Abbreviations

Acronym	Description
CMOS	Complementary Metal Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MIL	Military
MM	Machine Model
TTL	Transistor-Transistor Logic

## 15. Revision history

Table 12. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74LVC1G07_Q100 v.1	20130523	Product data sheet	-	-

## 16. Legal information

### 16.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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Product [short] data sheet	Production	This document contains the product specification.

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[2] The term 'short data sheet' is explained in section "Definitions".

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